

## PATENT ASSIGNMENT COVER SHEET

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<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
CHIH-MING CHIU	02/25/2021
KAI-WEN CHENG	02/25/2021
YU-YI LIN	02/25/2021
YI-HSUAN FAN	02/25/2021
<b>RECEIVING PARTY DATA</b>	
<b>Name:</b>	REALTEK SEMICONDUCTOR CORP.
<b>Street Address:</b>	NO.2, INNOVATION RD. II, HSINCHU SCIENCE PARK
<b>City:</b>	HSINCHU
<b>State/Country:</b>	TAIWAN
<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
Application Number:	17188303
<b>CORRESPONDENCE DATA</b>	
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<b>NAME OF SUBMITTER:</b>	TUYEN LY
<b>SIGNATURE:</b>	/tuyen ly/
<b>DATE SIGNED:</b>	03/01/2021
<b>Total Attachments: 3</b>	
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## COMBINED DECLARATION AND ASSIGNMENT

Title of Invention: NETWORK SWITCH AND NETWORK SWITCH SYSTEM  
THEREOF

As a below named inventor, I hereby declare that:

This declaration is directed to:

The attached application; or  
 United States application number or PCT international application number \_\_\_\_\_,  
filed on \_\_\_\_\_.

The above-identified application was made or authorized to be made by me.

I believe that I am the original inventor or an original joint inventor of a claimed invention in the application.

I hereby acknowledge that any willful false statement made in this declaration is punishable under 18 U.S.C. 1001 by fine or imprisonment of not more than five (5) years, or both.

WHEREAS, REALTEK SEMICONDUCTOR CORP. of No.2, Innovation Rd. II, Hsinchu Science Park, HsinChu, Taiwan, R.O.C., its heirs, successors, legal representatives and assigns (hereinafter designated as the Assignee) is desirous of acquiring the entire right, title and interest in and to said invention and in and to any Letters Patent(s) that may be granted therefor in the United States of America and  in any foreign countries.

NOW, THEREFORE, in consideration of the sum of Ten Dollars (\$10.00) to the undersigned in hand paid, the receipt of which is hereby acknowledged, and other good and valuable consideration, the undersigned has (have) sold, assigned and transferred, and by these presents does sell, assign and transfer unto said Assignee the full and exclusive right to the said invention in the United States of America, its territories, dependencies and possessions and the entire right, title and interest in and to any and all Letters Patent(s) which may be granted therefor in the United States of America, its territories, dependencies and possessions, and if the box above is designated, in any and all foreign countries; and to any and all divisions, reissues,

continuations, conversions and extensions thereof for the full term or terms for which the same may be granted.

The undersigned agree(s) to execute all papers necessary in connection with this application and any continuing, divisional, conversion or reissue applications thereof and also to execute separate assignments in connection with such applications as the Assignee may deem necessary or expedient.

The undersigned agree(s) to execute all papers necessary in connection with any interference which may be declared concerning this application or continuation, division, conversion or reissue thereof or Letter Patent(s) or reissue patent issued thereon and to cooperate with the Assignee in every way possible in obtaining and producing evidence and proceeding with such interference.

The undersigned agree(s) to execute all papers and documents and to perform any act which may be necessary in connection with claims or provisions of the International Convention for the Protection of Industrial Property or similar agreements.

The undersigned agree(s) to perform all affirmative acts which may be necessary to obtain a grant of a valid United States of America patent(s) or a grant of a valid United States of America and any foreign patent(s) to the Assignee and to vest all rights therein hereby conveyed to said Assignee as fully and entirely as the same would have been held by the undersigned if this Assignment and sale had not been made.

The undersigned hereby authorize(s) and request(s) the Patent and Trademark Office Officials in the United States of America and in any foreign countries to issue any and all Letters Patents resulting from said application or any continuing, divisional, conversion or reissue applications thereof to the said Assignee, as Assignee of the entire interest, and hereby covenants that he has (they have) the full right to convey the entire interest herein assigned, and that he has (they have) not executed, and will not execute, any agreement in conflict herewith.

The undersigned hereby covenant(s) that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment.

In witness whereof, executed by the undersigned on the date(s) opposite the undersigned name(s).

LEGAL NAME OF FIRST OR SOLE INVENTOR:

Chiu, Chih-Ming

Signature: Chiu Chih Ming Date: February 25, 2021

LEGAL NAME OF ADDITIONAL JOINT INVENTOR, IF ANY:

Cheng, Kai-Wen

Signature: Cheng Kai-Wen Date: February 25, 2021

LEGAL NAME OF ADDITIONAL JOINT INVENTOR, IF ANY:

Lin, Yu-Yi

Signature: Yu-Yi Lin Date: February 25, 2021

LEGAL NAME OF ADDITIONAL JOINT INVENTOR, IF ANY:

Fan, Yi-Hsuan

Signature: Fan Yi-Hsuan Date: February 25, 2021

Additional inventors are being named on separately numbered sheets attached hereto.